COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP40312</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>TID #: PMP40312</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 11/6/2017 10:39:07 AM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
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